

Report Information

More information from: <https://www.marketresearchfuture.com/reports/chip-on-flex-market-2015>

Chip On Flex Market Research Report - Global Forecast to 2030

Report / Search Code: MRFR/SEM/1483-CR

Publish Date: January, 2017

Request Sample

Price	1-user PDF : \$ 4950.0	Enterprise PDF : \$ 7250.0
-------	------------------------	----------------------------

Description:

Global Chip on Flex (COF) Market Size and Synopsis:

Market Scenario:

Chip-on-Flex refers to the semiconductor assembly technology wherein the microchip or die is directly mounted on and electrically connected to a flexible circuit which is a circuit built on a flexible substrate instead of the usual printed circuit board. The shorter interconnection paths on chip on flex simplifies the process of designing and manufacturing the product and improving its performance. Chip on flex has some important features such as heat sinks, component assembly, penalization, shielding, over molding and graphic overlay among others which makes it more acceptable among end users such as electronic industry, aerospace, defense and others. The major drivers for the growth of this market are increasing need for small and flexible electronics in various applications such as displays, sensors, lighting, biomedical implants, and radio frequency identification among others and the rapid technological advancements which lead to accurate designs and automated production, of flex circuits that helps to eliminate human errors once involved in hand-built wire harnesses. With the use of these flexible circuit board companies ensure the 100% efficiency in the products, due to which level of fault ratio is drastically reduced. Flex chips help in reducing the cost, improving operator ergonomics, amplified product quality and testing repeatability.

The Global Chip-on-Flex Market Size is expected to grow from US ~\$1437 Million in 2016 to USD 1,868.63 Million by 2030, at an estimated CAGR of 3.7% . The Chip on Flex market growth can be constrained by the increased cost of raw materials in related industries like the electronic industry along with the wide variety of technology used and the consumer needs changing to efficient, cheaper and powerful consumer electronics and mobile technologies.

Study Objectives of Global Chip on Flex (COF) Market:

- To provide detailed analysis of the market structure along with forecast of the various segments and sub-segments of the global chip on flex market.
- To provide insights about factors affecting the market growth.
- To analyze the global chip on flex Industry based porter's five force analysis etc.
- To provide historical and forecast revenue of the market segments and sub-segments with respect to four main geographies and their countries- North America, Europe, Asia, and Rest of the World (ROW).
- To provide country level analysis of the market with respect to the current market size and future prospective.
- To provide country level analysis of the market for segment by types, applications and verticals.
- To provide strategic profiling of key players in the market, comprehensively analyzing their core competencies, and drawing a competitive landscape for the market.
- To track and analyze competitive developments such as joint ventures, strategic alliances, mergers and acquisitions, new product developments, and research and developments in the Global chip on flex Market.

Key Finding:

- The Global Chip on Flex Market is expected to reach USD 1,868.63 Million by 2030.
- Europe accounts for the largest market share and is growing with a market share of USD 1,868.63 Million during forecast period.

- China accounts highest production capacity in the year 2016
- Global Chip on flex Industry is segmented by type that includes single sided COF and Others. Out of which single sided COF captures 94.43% of market share.

Key Players and Market Share Insights

The prominent players in the market of chip on flex (COF) market are – LGIT corporation (U.S.), Stemko group(Korea), Flexceed(Japan) , Chipbond technology corporation(Taiwan), CWE(Taiwan), Danbond technology co. ltd.(China), AKM industrial company ltd.(China), compass technology company limited(Hong Kong), Compunetics(U.S.), and Stars microelectronics public company ltd (Thailand) among others.

Market Segmentation:

The Global chip on flex Market has been segmented on the basis of types, applications and verticals. The types of chip on flex are one sided chip on flex and others. The COF applications comprises of static and dynamic flexing. The various verticals of chip on flex market are military, medical, aerospace, electronics and others.

Market Regional Analysis

The regional analysis of chip on flex market is being studied for areas such as Asia pacific, North America, Europe and rest of the world. Asia pacific is expected to record highest growth rate owing to existence of large number of chip on flex manufacturers in china like Danbond Technology, AKM Industrial, Compass Technology Company and others. Asia pacific will be followed by North America owing to increased adoption of new technologies especially in automobile sector. American depository of shares is also helping in mergers of various organizations to enhance the production capabilities in chip on flex market. Many well established firms such as AKM Industrial, Compunetics and others are increasing their sales area in the Europe region which will lead to the growth of Europe region in chip on flex market.

Intended Audience

- COF manufactures
- Industries such as aerospace, automotive, IT, industrial, and medical, among others
- Government institutions
- Research institutions
- Adhesive manufacturers
- Conductor and insulator manufacturers like silver, copper and others

Table of Content:

Contents
1 MARKET INTRODUCTION
1.1 INTRODUCTION
1.2 SCOPE OF STUDY
1.2.1 RESEARCH OBJECTIVE
1.2.2 ASSUMPTIONS
1.2.3 LIMITATIONS
1.3 MARKET STRUCTURE
2 RESEARCH METHODOLOGY
2.1 RESEARCH NETWORK SOLUTION
2.2 PRIMARY RESEARCH
2.3 SECONDARY RESEARCH
2.4 FORECAST MODEL
2.4.1 MARKET DATA COLLECTION, ANALYSIS & FORECAST
2.4.2 MARKET SIZE ESTIMATION
3 MARKET DYNAMICS
3.1 INTRODUCTION
3.2 MARKET DRIVERS
3.3 MARKET CHALLENGES
3.4 MARKET OPPORTUNITIES
3.5 MARKET RESTRAINTS
4 EXECUTIVE SUMMARY
5 MARKET FACTOR ANALYSIS
5.1 PORTER'S FIVE FORCES ANALYSIS
5.2 SUPPLY CHAIN ANALYSIS
6 GLOBAL CHIP ON FLEX MARKET, BY SEGMENTS
6.1 INTRODUCTION
6.2 MARKET STATISTICS
6.2.1 BY TYPE
6.2.1.1 ONE SIDED CHIP ON FLEX
6.2.1.2 OTHERS
6.2.2 BY APPLICATIONS
6.2.2.1 STATIC
6.2.2.2 DYNAMIC FLEXING
6.2.3 BY VERTICALS

6.2.3.1 MILITARY
6.2.3.2 MEDICAL
6.2.3.4 AEROSPACE
6.2.3.5 ELECTRONICS
6.2.3.6 OTHERS
6.2.4 BY GEOGRAPHY
6.2.4.1 NORTH AMERICA
6.2.4.2 EUROPE
6.2.4.3 ASIA-PACIFIC
6.2.4.4 REST OF THE WORLD

7 COMPETITIVE ANALYSIS
7.1 MARKET SHARE ANALYSIS
7.2 COMPANY PROFILES
7.2.1 LGIT CORPORATION (U.S.)
7.2.2 STEMKO GROUP (KOREA)
7.2.3 FLEXCEED (JAPAN)
7.2.4 CHIPBOND TECHNOLOGY CORPORATION (TAIWAN)
7.2.5 CWE (TAIWAN)
7.2.6 DANBOND TECHNOLOGY CO. LTD. (CHINA)
7.2.7 AKM INDUSTRIAL COMPANY LTD. (CHINA)
7.2.8 COMPASS TECHNOLOGY COMPANY LIMITED (HONG KONG)
7.2.9 COMPUNETICS (U.S.)
7.2.10 STARS MICROELECTRONICS PUBLIC COMPANY LTD (THAILAND)

8 List of Tables

TABLE 1 GLOBAL CHIP ON FLEX MARKET, BY TYPE
TABLE 2 GLOBAL CHIP ON FLEX MARKET, BY APPLICATIONS
TABLE 3 GLOBAL CHIP ON FLEX MARKET, BY VERTICALS
TABLE 4 GLOBAL CHIP ON FLEX MARKET, BY REGIONS
TABLE 5 NORTH AMERICA CHIP ON FLEXMARKET, BY TYPE
TABLE 6 NORTH AMERICA CHIP ON FLEX MARKET, BY APPLICATIONS
TABLE 7 NORTH AMERICA CHIP ON FLEX MARKET, BY VERTICALS
TABLE 8 U.S. CHIP ON FLEX MARKET, BY TYPE
TABLE 9 U.S. CHIP ON FLEX MARKET, BY APPLICATIONS
TABLE 10 U.S. CHIP ON FLEX MARKET, BY VERTICALS
TABLE 11 CANADA CHIP ON FLEX MARKET, BY TYPE
TABLE 12 CANADA CHIP ON FLEX MARKET, BY APPLICATIONS
TABLE 13 CANADA CHIP ON FLEX MARKET, BY VERTICALS
TABLE 14 EUROPE CHIP ON FLEX MARKET, BY TYPE
TABLE 15 EUROPE CHIP ON FLEX MARKET, BY APPLICATIONS
TABLE 16 EUROPE CHIP ON FLEX MARKET, BY VERTICALS
TABLE 17 GERMANY CHIP ON FLEX MARKET, BY TYPE
TABLE 18 GERMANY CHIP ON FLEX MARKET, BY APPLICATIONS
TABLE 19 GERMANY CHIP ON FLEX MARKET, BY VERTICALS
TABLE 20 FRANCE CHIP ON FLEX MARKET, BY TYPE
TABLE 21 FRANCE CHIP ON FLEX MARKET, BY APPLICATIONS
TABLE 22 FRANCE CHIP ON FLEX MARKET, BY VERTICALS
TABLE 23 U.K. CHIP ON FLEX MARKET, BY TYPE
TABLE 24 U.K. CHIP ON FLEX MARKET, BY APPLICATIONS
TABLE 25 U.K. CHIP ON FLEX MARKET, BY VERTICALS
TABLE 26 REST OF EUROPE CHIP ON FLEX MARKET, BY TYPE
TABLE 27 REST OF EUROPE CHIP ON FLEX MARKET, BY APPLICATIONS
TABLE 28 REST OF EUROPE CHIP ON FLEX MARKET, BY VERTICALS
TABLE 29 ASIA-PACIFIC CHIP ON FLEX MARKET, BY TYPE
TABLE 30 ASIA-PACIFIC CHIP ON FLEX MARKET, BY APPLICATIONS
TABLE 31 ASIA-PACIFIC CHIP ON FLEX MARKET, BY VERTICALS
TABLE 32 MIDDLE EAST & AFRICA CHIP ON FLEX MARKET, BY TYPE
TABLE 33 MIDDLE EAST & AFRICA CHIP ON FLEX MARKET, BY APPLICATIONS
TABLE 34 MIDDLE EAST & AFRICA CHIP ON FLEX MARKET, BY VERTICALS

9 List of Figures

FIGURE 1 RESEARCH NETWORK SOLUTION
FIGURE 2 GLOBAL CHIP ON FLEX MARKET: BY TYPE (%)
FIGURE 3 GLOBAL CHIP ON FLEX MARKET: BY APPLICATIONS (%)
FIGURE 4 GLOBAL CHIP ON FLEX MARKET: BY VERTICALS (%)
FIGURE 5 GLOBAL CHIP ON FLEX MARKET: BY REGION
FIGURE 6 NORTH AMERICA CHIP ON FLEX MARKET, BY TYPE (%)
FIGURE 7 NORTH AMERICA CHIP ON FLEX MARKET, BY APPLICATIONS (%)
FIGURE 8 NORTH AMERICA CHIP ON FLEX MARKET, BY VERTICALS (%)
FIGURE 9 EUROPE CHIP ON FLEX MARKET, BY TYPE (%)
FIGURE 10 EUROPE CHIP ON FLEX MARKET, BY APPLICATIONS (%)
FIGURE 11 EUROPE CHIP ON FLEX MARKET, BY VERTICALS (%)
FIGURE 12 ASIA-PACIFIC CHIP ON FLEX MARKET, BY TYPE (%)
FIGURE 13 ASIA-PACIFIC CHIP ON FLEX MARKET, BY APPLICATIONS (%)
FIGURE 14 ASIA-PACIFIC CHIP ON FLEX MARKET, BY VERTICALS (%)
FIGURE 15 ROW CHIP ON FLEX MARKET, BY TYPE (%)
FIGURE 16 ROW CHIP ON FLEX MARKET, BY APPLICATIONS (%)
FIGURE 17 ROW CHIP ON FLEX MARKET, BY VERTICALS (%)